



APPROVAL SHEET

| Approval Specification | Customer's Approval Certificate |
|--|---|
| <p>TO:</p> <p>Part No.:</p> <p>Customer's Part No.:</p> | <p>Please return this copy as a certification of your approval</p> <p>Checked & Approved by:</p> <p>Date:</p> |

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| | | |
|----------|---|-----------|
| Part No. | : | SF0236 |
| Pages | : | 6 |
| Date | : | 2013/6/19 |
| Revision | : | 1.0 |

| | |
|---------------------|-----|
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| Checked by: | |
| Approved by: | |

Application

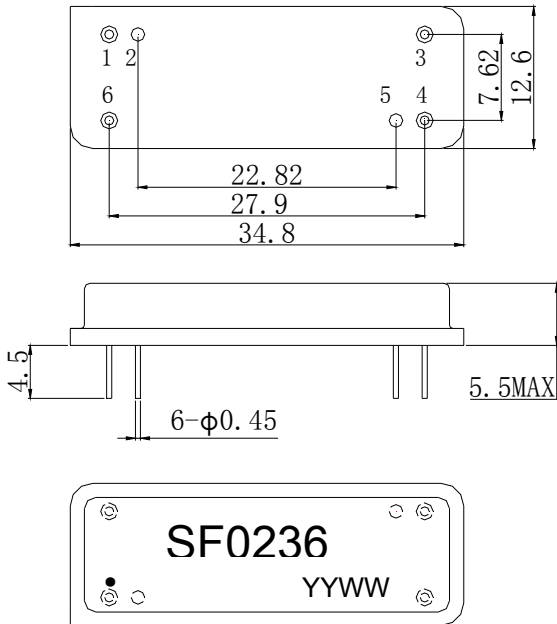
- Low amplitude ripple
- Sharp rejections at both out-bands
- Usable passband 30 MHz
- Low Shape Factor

Features

- RoHS compatible
- Package size 34.8x12.6x5.50mm³
- Package Code DIP3512J
- Electrostatic Sensitive Device(ESD)



Package Dimensions (Unit: mm)



Pin Configuration

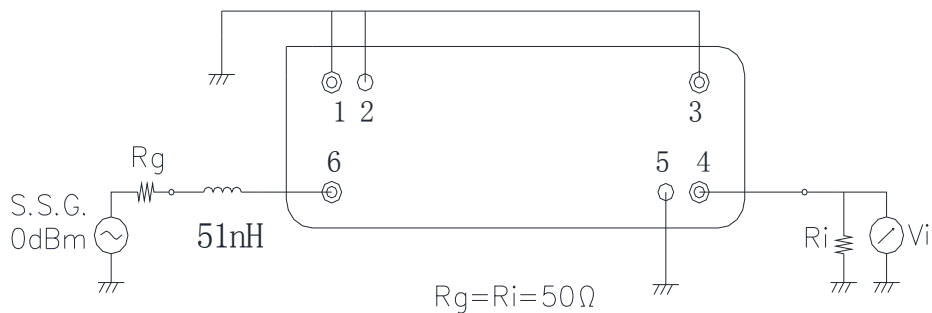
| Pin No. | Description |
|---------|-------------|
| 6 | Input |
| 4 | Output |
| 1,2,3,5 | Ground |

Marking Description

| | |
|-------------|-----------------------|
| S | Trademark |
| F | SAW Filter |
| 0236 | Part Number |
| ● | Pin 1 |
| YYWW | Year Code & Week Code |

*Fig: If the products produced in 06th week of 2012, The year code & week code is 1206.

Test Circuit



Performance**Maximum Rating**

| Item | | Value | Unit |
|-----------------------|-----------|------------|------|
| DC Voltage | V_{DC} | 3 | V |
| Operation Temperature | T | -40 ~ +85 | °C |
| Storage Temperature | T_{stg} | -55 ~ +125 | °C |
| RF Power Dissipation | P | 10 | dBm |

Electronic Characteristics

Test Temperature: $25^{\circ}\text{C} \pm 2^{\circ}\text{C}$

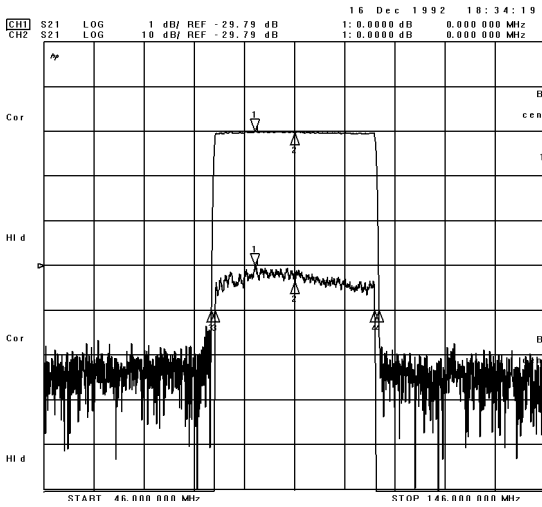
Terminating source impedance: 50Ω

Terminating load impedance: 50Ω

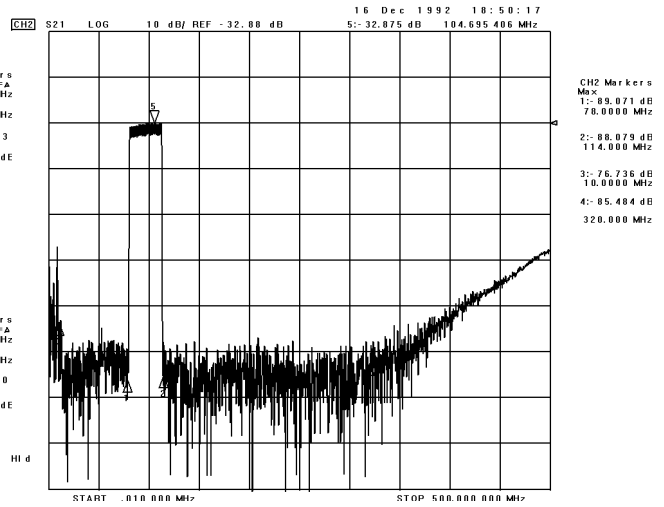
| Item | | Minimum | Typical | Maximum | Unit |
|---|-------------------|---------|---------|---------|------|
| Center Frequency | fc | | 96.0 | | MHz |
| Insertion Loss(min) | IL | | 29.8 | 30.0 | dB |
| Amplitude Ripple (p-p) 81.00-111.00MHz | $\Delta\alpha$ | | 0.7 | 1.0 | dB |
| 3 dB Bandwidth | BW_{3dB} | 30.72 | 32.1 | | MHz |
| Absolute Attenuation | α | | | | |
| | 30.00 -78.00 MHz | 45.0 | 47.0 | | dB |
| | 114.00-300.00 MHz | 45.0 | 48.0 | | dB |

Frequency Characteristics

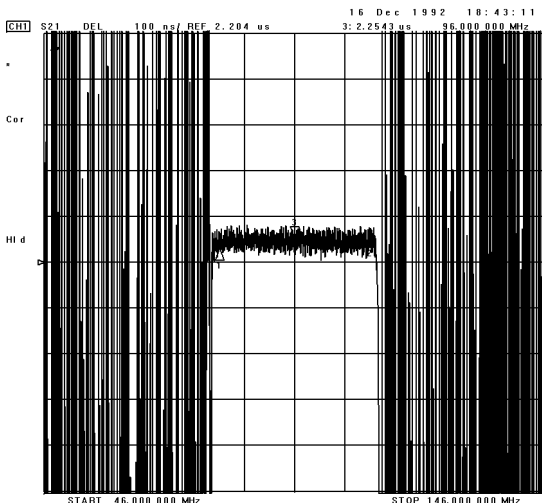
Frequency Response



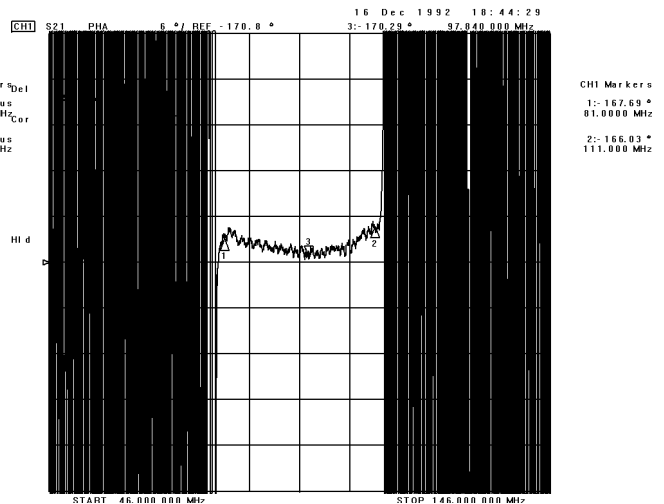
Frequency Response (wideband)



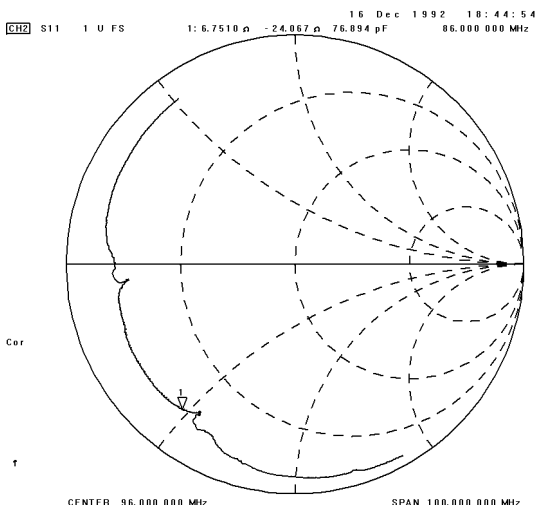
Delay Ripple



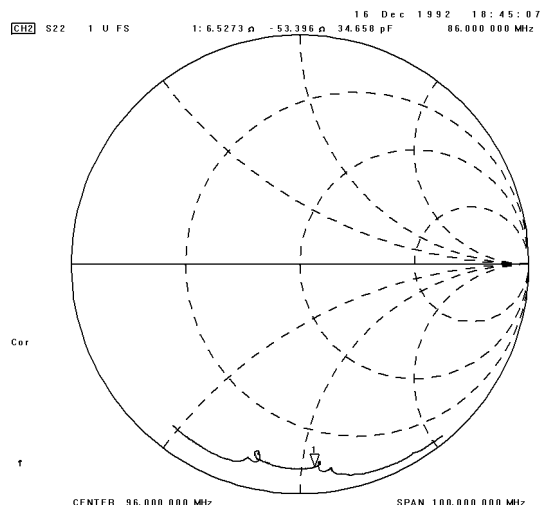
Phase Linearity



S11 Smith Chart



S22 Smith Chart



Reliability (The SAW components shall remain electrical performance after tests)

| No. | Test item | Test condition |
|-----|------------------------------|--|
| 1 | Temperature Storage | (1) Temperature: 85°C±2°C , Duration: 250h , Recovery time: 2h±0.5h (2) Temperature: -55°C±3°C , Duration: 250h ,Recovery time: 2h±0.5h |
| 2 | Humidity Test | Conditions: 60°C±2°C , 90~95% RH Duration: 250h |
| 3 | Thermal Shock | Heat cycle conditions: TA=-55°C±3°C, TB=85°C±2°C, t1=t2=30min, Switch time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h. |
| 4 | Vibration Fatigue | Frequency of vibration: 10~55Hz Amplitude:1.5mm Directions: X,Y and Z Duration: 2h |
| 5 | Drop Test | Cycle time: 10 times Height: 1.0m |
| 6 | Solder Ability Test | Temperature: 245°C±5°C Duration: 3.0s--5.0s Depth: DIP--2/3 , SMD--1/5 |
| 7 | Resistance to Soldering Heat | (1)Thickness of PCB:1mm , Solder condition: 260°C±5°C , Duration: 10±1s (2)Temperature of Soldering Iron: 350°C±10°C , Duration: 3~4s , Recovery time : 2 ± 0.5h |

Recommended Reflow Soldering Diagram



Notes

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.